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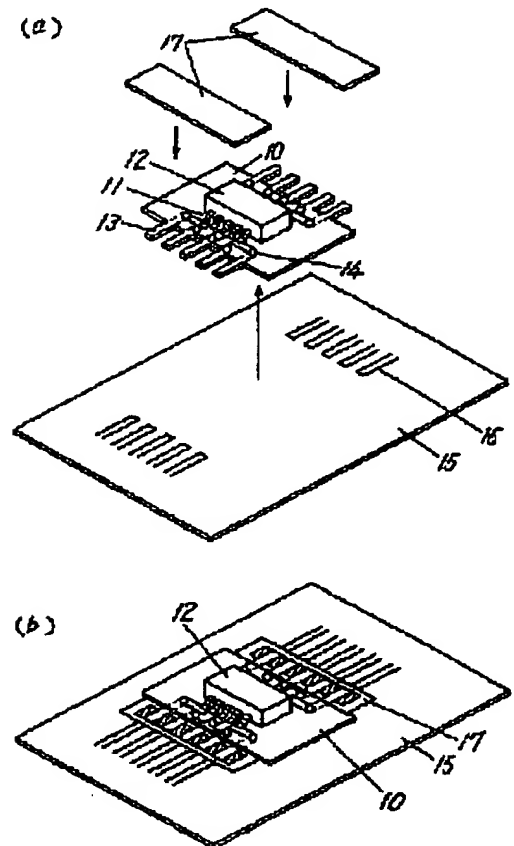
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TITLE : MOUNTING OF ELECTRONIC
COMPONENT ON FLEXIBLE WIRING
BOARD



ABSTRACT : PROBLEM TO BE SOLVED: To provide a method of mounting an electronic component on a flexible wiring board(FPC) which is used for various types of electronic equipments, which can mount the electronic component to be connected by a reflow soldering method on the low-cost printed FPC.

SOLUTION: A first connection part 13 in a comb-teeth shape on a copper-clad FPC, which is a first flexible wiring board 10 connected with an electronic component 12 by a reflow soldering method, is superposed on a second connection part 16 on a printed FPC, which is a second flexible wiring board 15. An insulating film 17 consisting of the same material as that for the board 15 is made to cover on the connection part 13 from the upper surface of the connection part 13, and the peripheral edges of the connection parts 13 and 16 are fixed by welding. As a result, the component 12 can be mounted on the board 15 and a cost reduction in the whole mounting board is achieved.

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